

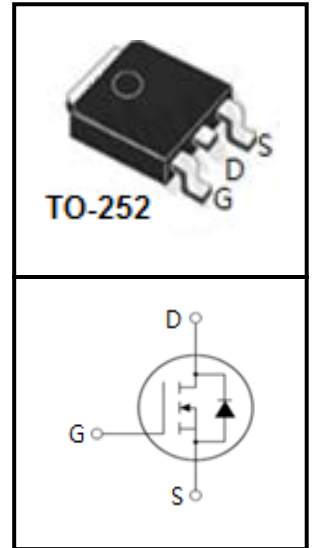
100V N-Channel Trench MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits



Device Marking and Package Information

Device	Package	Marking
CTD10N033	TO-252	CTD10N033

Absolute Maximum Ratings at $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0V$)	V_{DSS}	100	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note1)	I_D	30	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note1)		23	A
Pulsed Drain Current (note2)	I_{DM}	120	A
Gate Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy (note3)	E_{AS}	46	mJ
Power Dissipation $T_C = 25^\circ\text{C}$ (note4)	P_D	52	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.4	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0V, T _J = 25°C	--	--	1	uA
		V _{DS} = 80V, V _{GS} = 0V, T _J = 100°C	--	--	5	uA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V	--	--	±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	--	2.5	V
Drain-Source On-Resistance (note2)	R _{DS(on)}	V _{GS} = 10V, I _D = 15A	--	27.5	33	mΩ
		V _{GS} = 4.5V, I _D = 10A	--	29	37	mΩ
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz	--	3000	--	pF
Output Capacitance	C _{oss}		--	120	--	
Reverse Transfer Capacitance	C _{rss}		--	110	--	
Gate Resistance	Rg	f = 1.0MHz	--	1.7	--	Ω
Total Gate Charge	Q _g	V _{DS} = 80V, I _D = 15A, V _{GS} = 10V	--	65	--	nC
Gate-Source Charge	Q _{gs}		--	7	--	
Gate-Drain Charge	Q _{gd}		--	16	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} = 50V, I _D = 15A ,R _G = 3Ω	--	12	--	ns
Turn-on Rise Time	t _r		--	42	--	
Turn-off Delay Time	t _{d(off)}		--	54	--	
Turn-off Fall Time	t _f		--	13	--	
Body Diode Characteristics						
Continuous Body Diode Current	I _S	T _C = 25°C	--	--	30	A
Pulsed Diode Forward Current	I _{SM}		--	--	120	
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 15A, V _{GS} = 0V	--	--	1.2	V
Reverse Recovery Time	t _{rr}	I _S = 15A di _F /dt = 100A/μs	--	60	--	ns
Reverse Recovery Charge	Q _{rr}		--	140	--	nC

Notes

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{GS} = 50V, R_g = 25\Omega, L = 1mH$
4. The power dissipation is limited by 175°C junction temperature
5. The data is theoretically the same as I_D and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

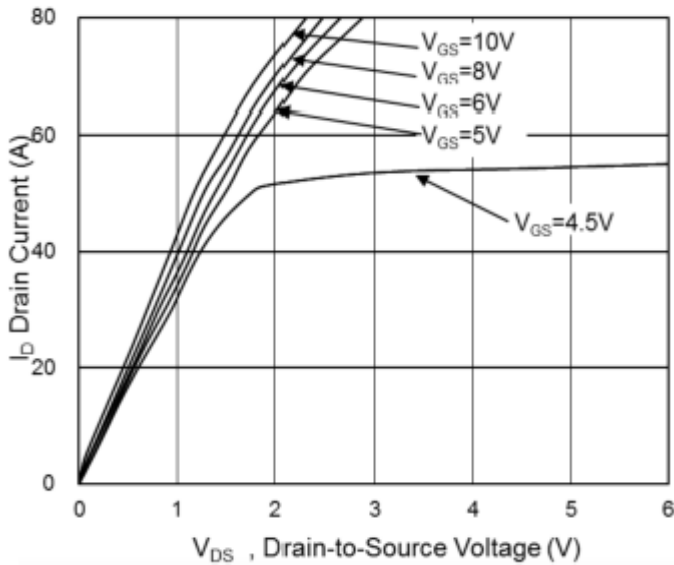


Fig.1 Typical Output Characteristics

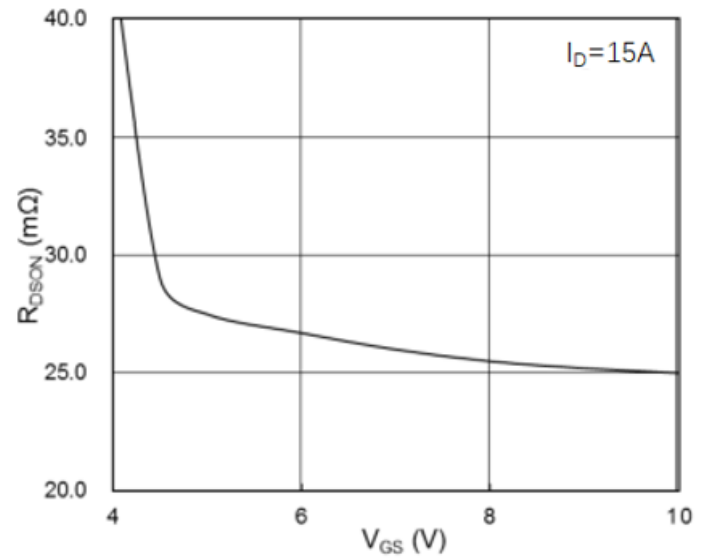


Fig.2 On-Resistance vs. G-S Voltage

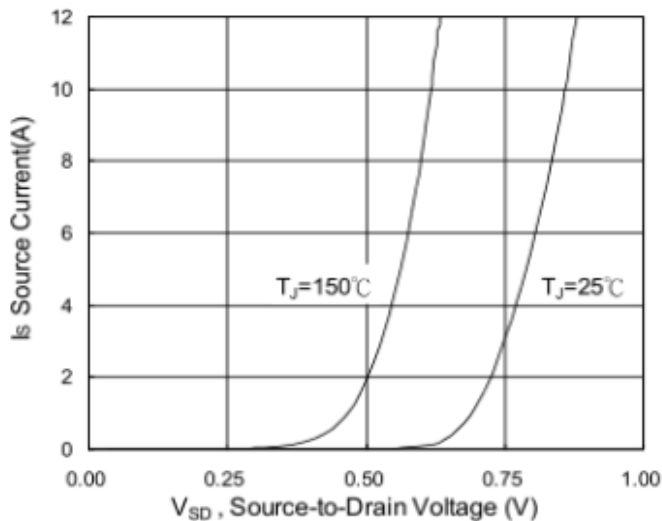


Fig.3 Forward Characteristics of Reverse Diode

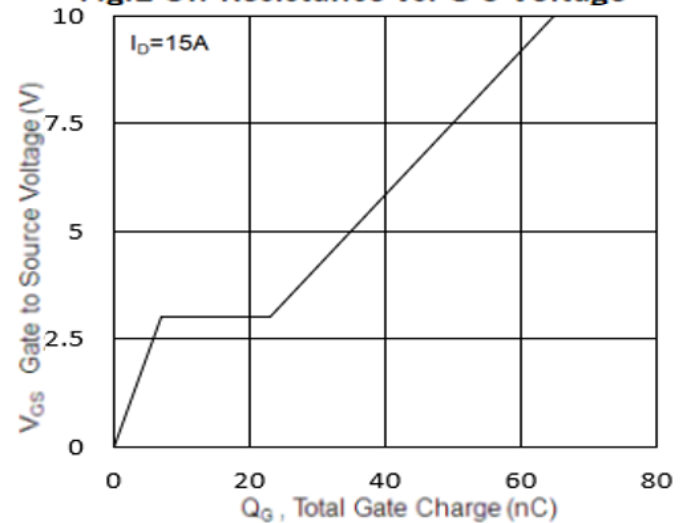


Fig.4 Gate-Charge Characteristics

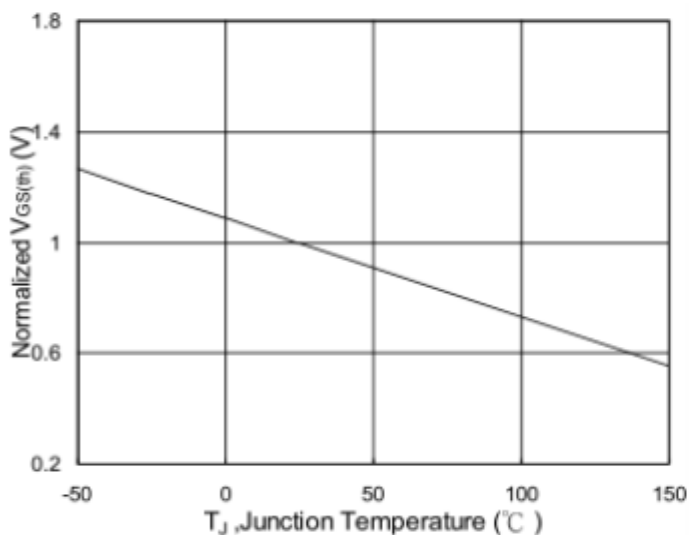


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

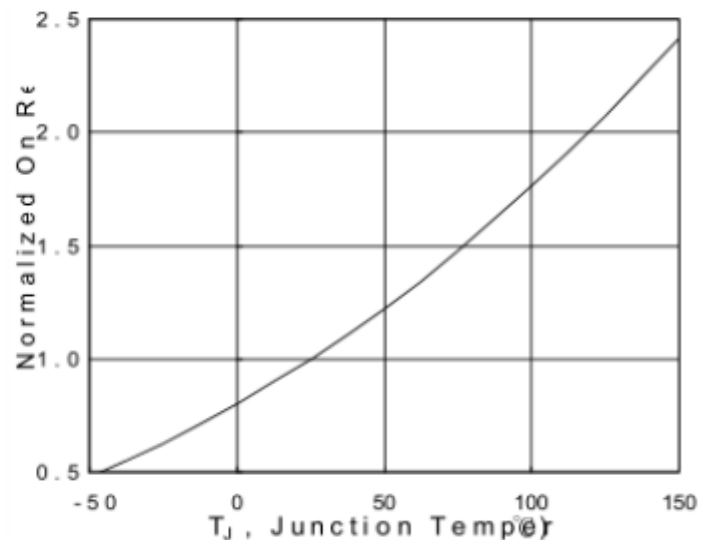


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

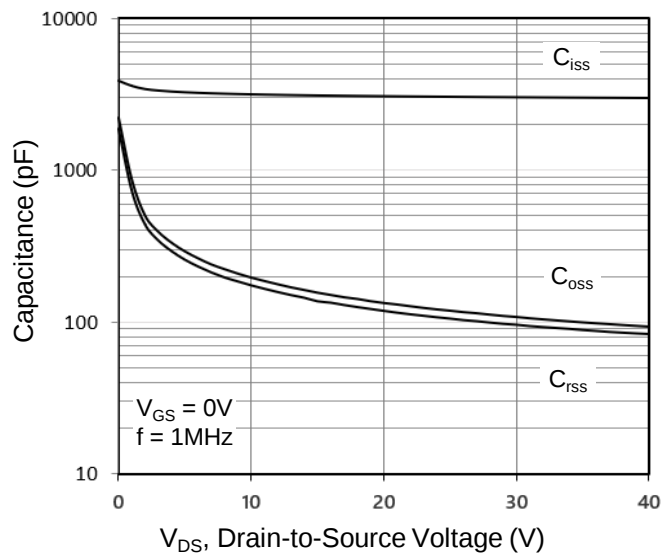


Fig.7 Capacitance

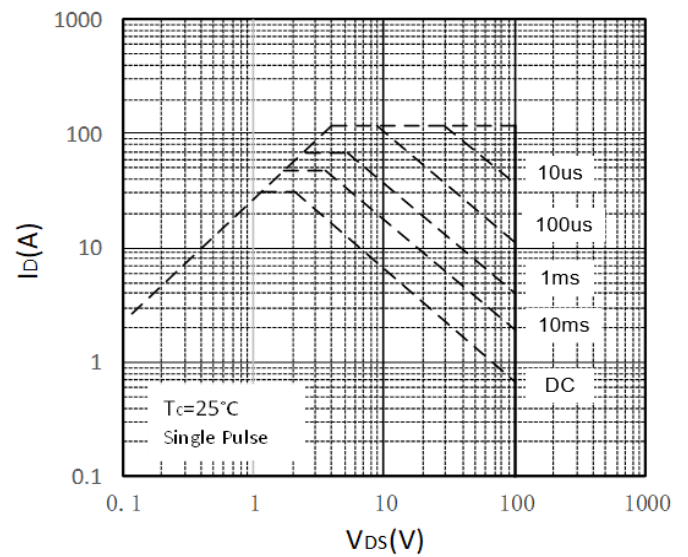


Fig.8 Safe Operating Area

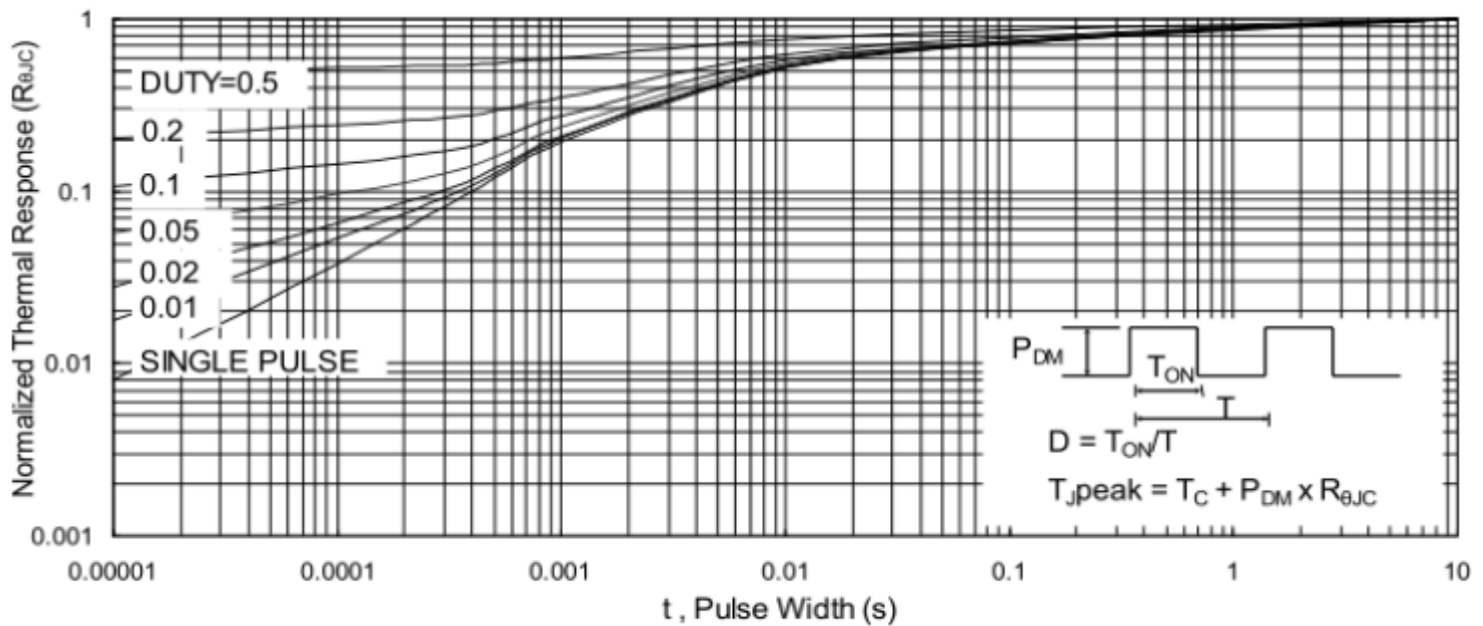
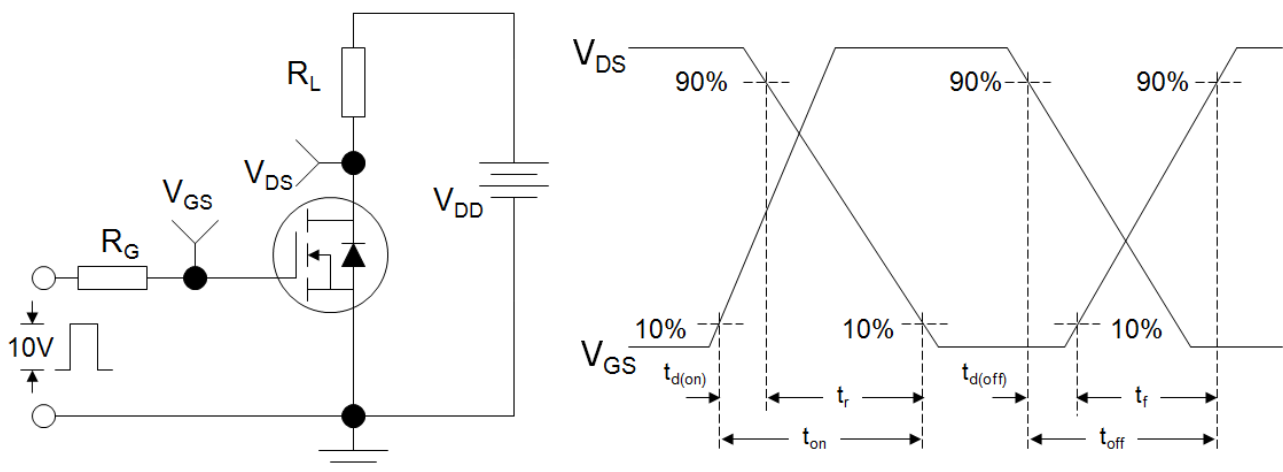
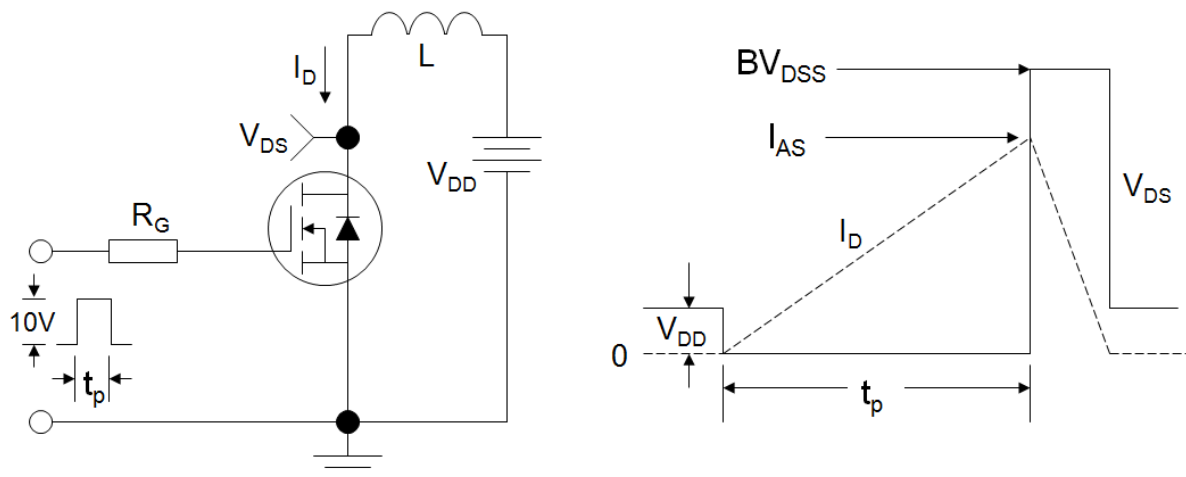
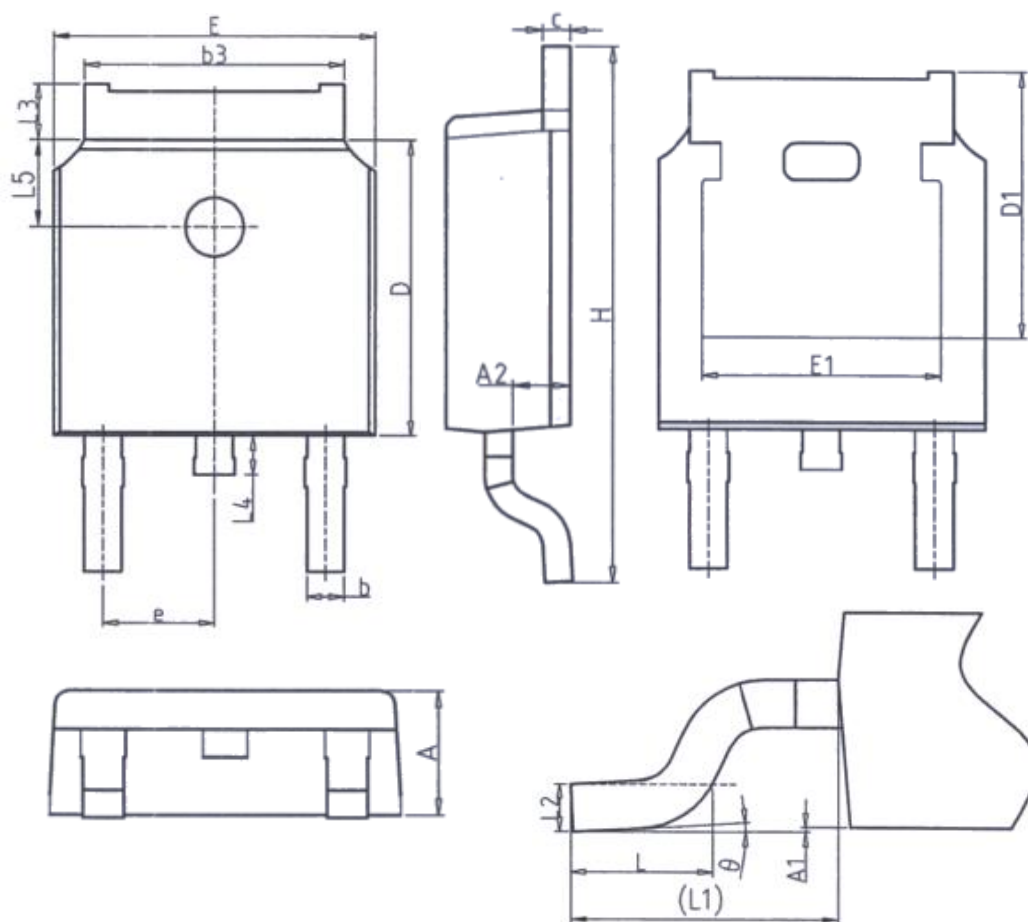


Fig.9 Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


TO-252



Unit: mm		
Symbol	Min.	Max.
A	2.20	2.40
A1	0.00	0.20
A2	0.97	1.17
b	0.68	0.90
b3	5.20	5.50
c	0.43	0.63
D	5.98	6.22
D1	5.30REF	
E	6.40	6.80
E1	4.63	—

Unit: mm		
Symbol	Min.	Max.
e	2.286BSC	
H	9.40	10.50
L	1.38	1.75
L1	2.90REF	
L2	0.51BSC	
L3	0.88	1.28
L4	—	1.00
L5	1.65	1.95
θ	0°	8°

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